



Monolithic Integration of O-band Photonic Transceivers in a “Zero-change” 32nm SOI CMOS

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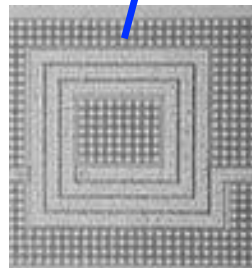
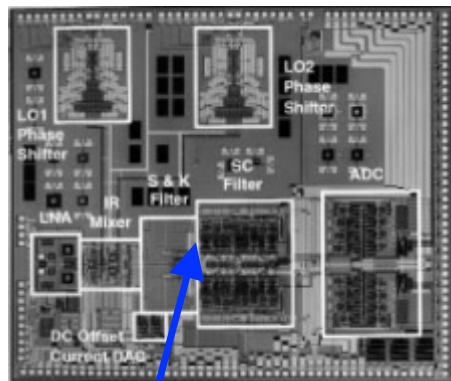
²Research Laboratory of Electronics, MIT

Monolithic Silicon Photonics

**Enhanced CMOS
enables new applications!**

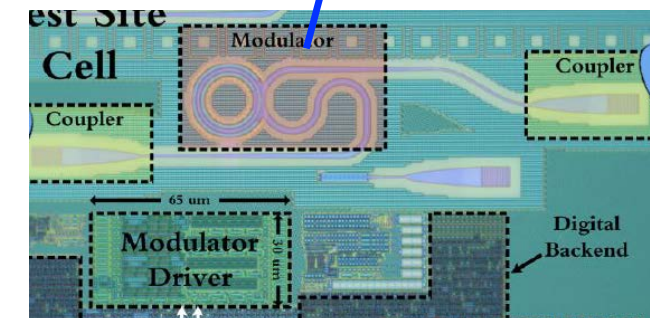
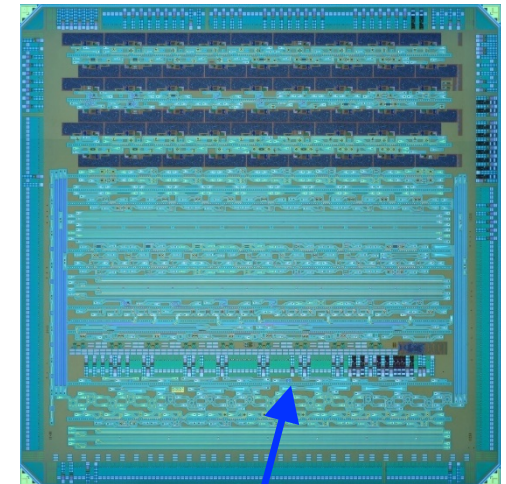
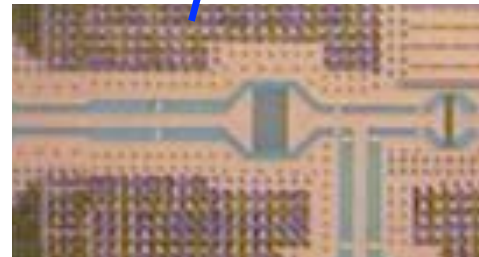
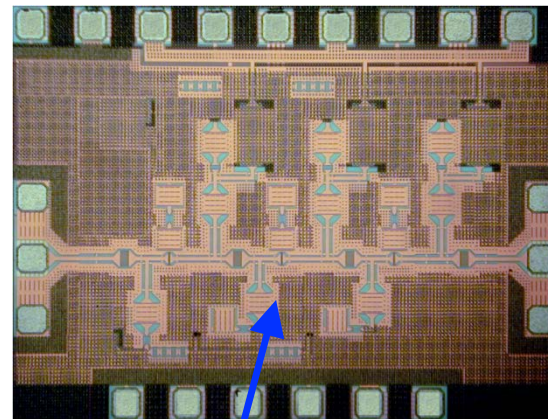
SiPh Transmitter in 45nm CMOS
Stojanovic, Popovic, Ram (2012)

CMOS Radios
Rudell & Gray (1997)

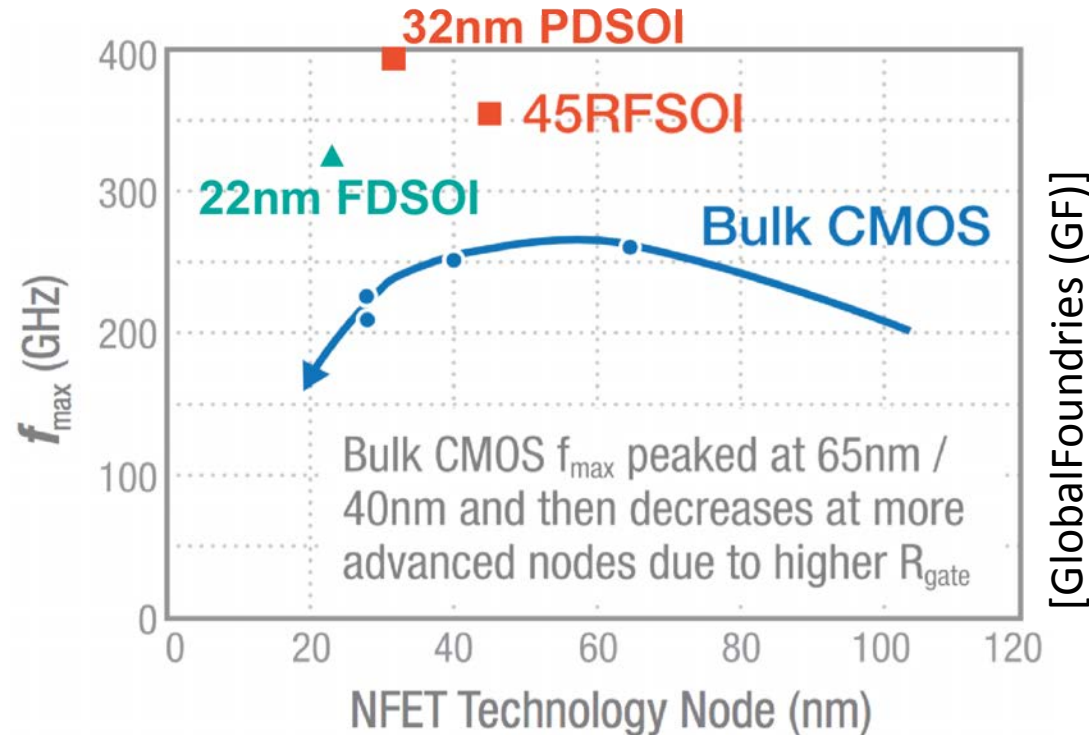


Inductors in IC
process
Nguyen & Meyer
1990

mmWave
CMOS Amplifier
Niknejad & Brodersen (2004)

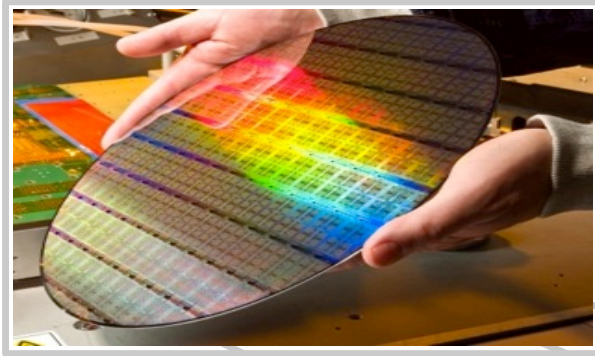


Photonics Next to The Fastest Transistors



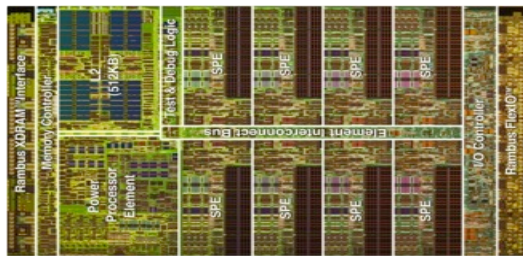
- f_T/f_{max} have not improved since 32nm node
- f_T/f_{max} affect speed, energy-efficiency, ... of electronic-photonic systems
- **32/45nm: Fastest Transistors + Thick-enough Si bodies to guide the light**
 - Si body in SOI nodes below 32nm (FDSOI) cannot guide the light!

IBM/GF SOI CMOS

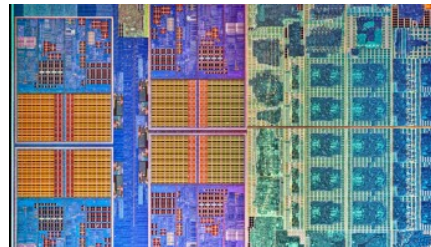


- 300mm wafer, commercial process
- MOSIS and TAPO MPW access
- Advanced processes used in microprocessors
- Photonic enhancement enables photonic SoC

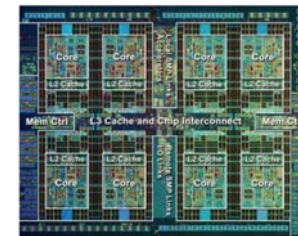
IBM Cell 45nm



AMD Llano APU 32nm

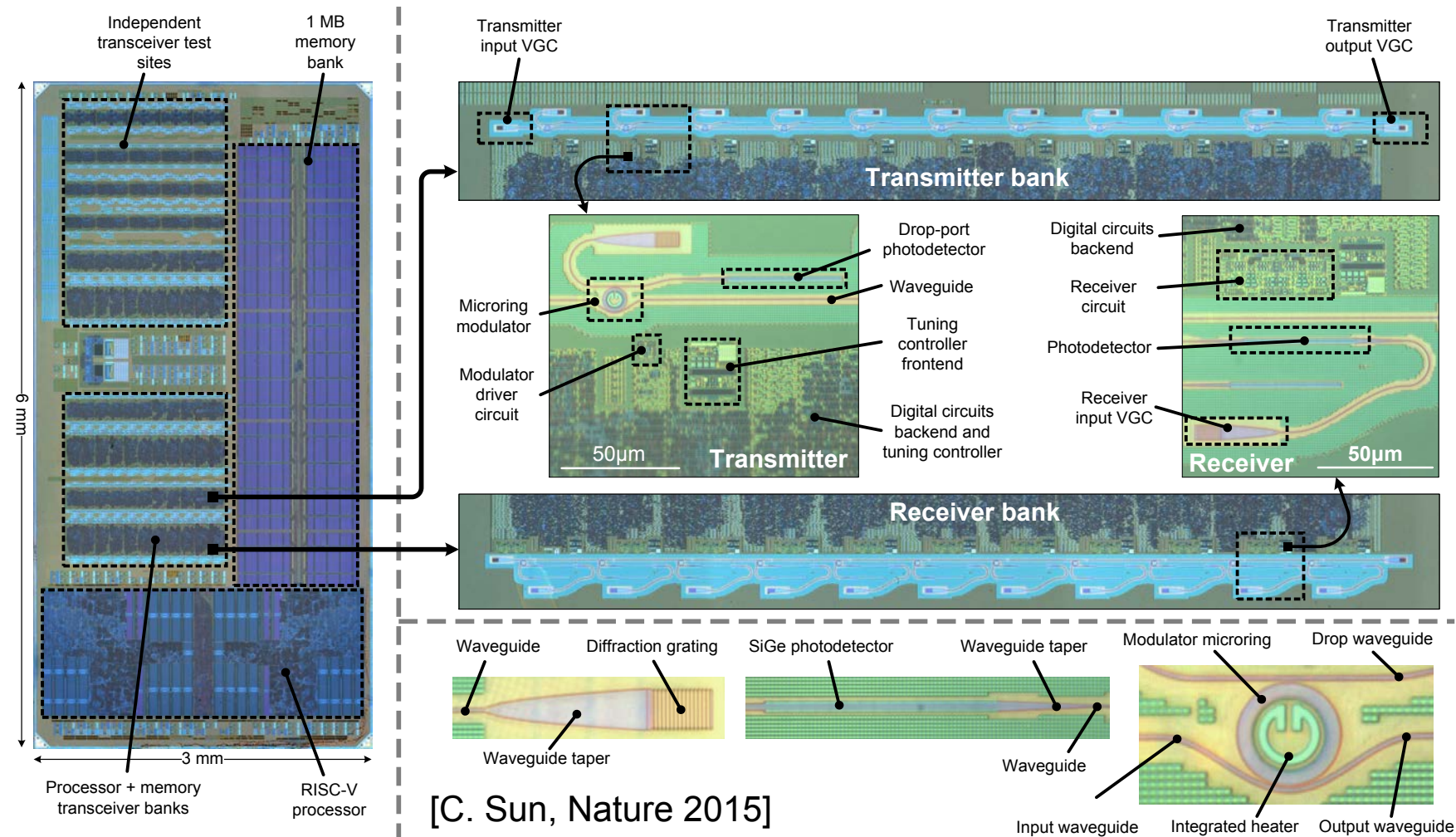


IBM Power 7+ 32nm

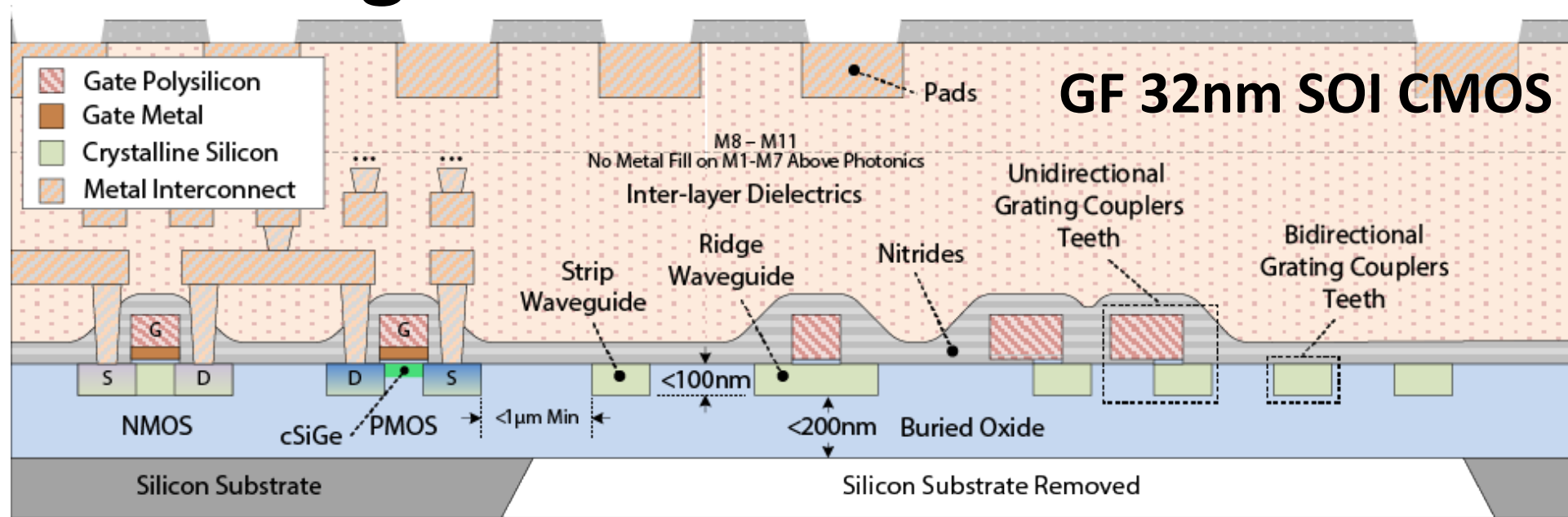


Photonic System-on-Chips in 45nm SOI

Millions of transistors + Hundreds of photonic devices!



“Zero-Change” Platforms

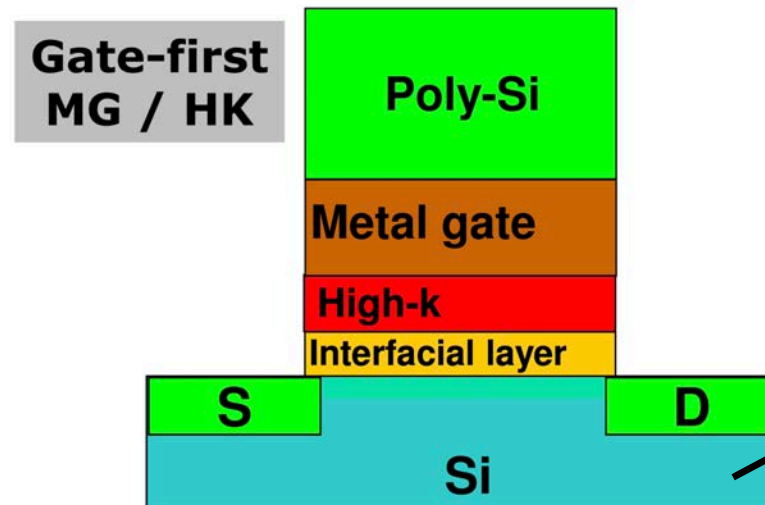


- Photonics for free! (No modification to the process)
- Closest proximity of electronics and photonics
- Single substrate removal post-processing step

Monolithic photonics platform with the fastest transistors

GF 32nm SOI CMOS

- First node with High-k/Metal gate (HKMG)
- 33% faster logic than 45nm node
- High-performance SoCs: AMD Lliano APU, Power 7+, ...
- Extra epitaxial SiGe layer to improve photonics

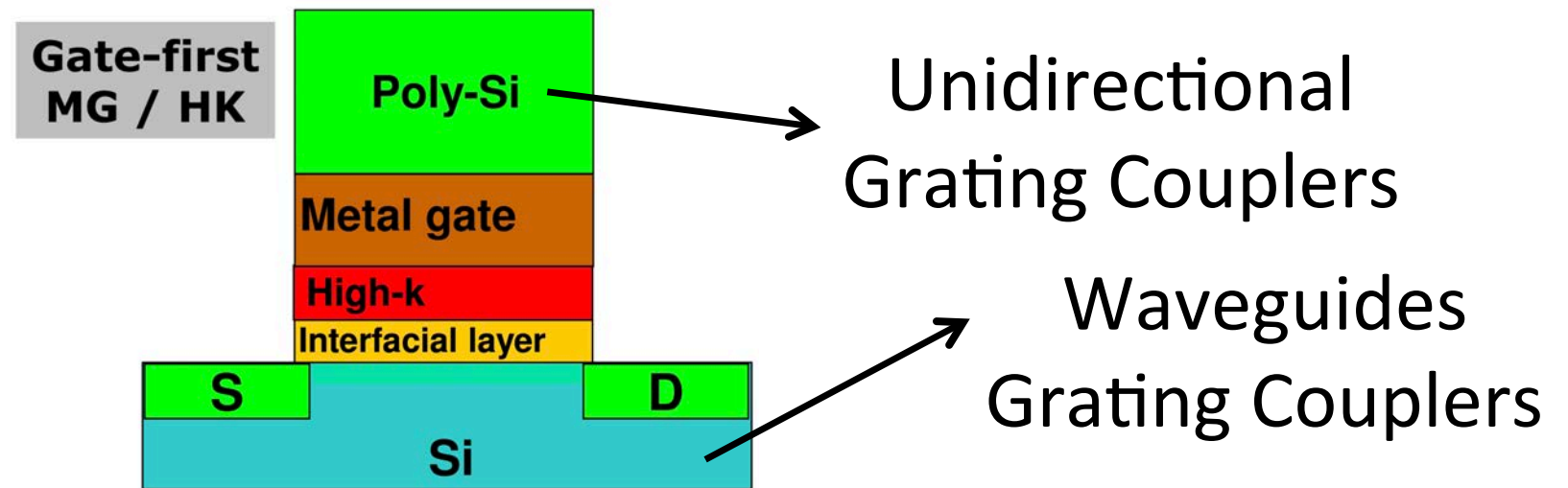


PMOS Cross-section [A. Kerber, SEMATECH AGST 2010]

Waveguides
Grating Couplers

GF 32nm SOI CMOS

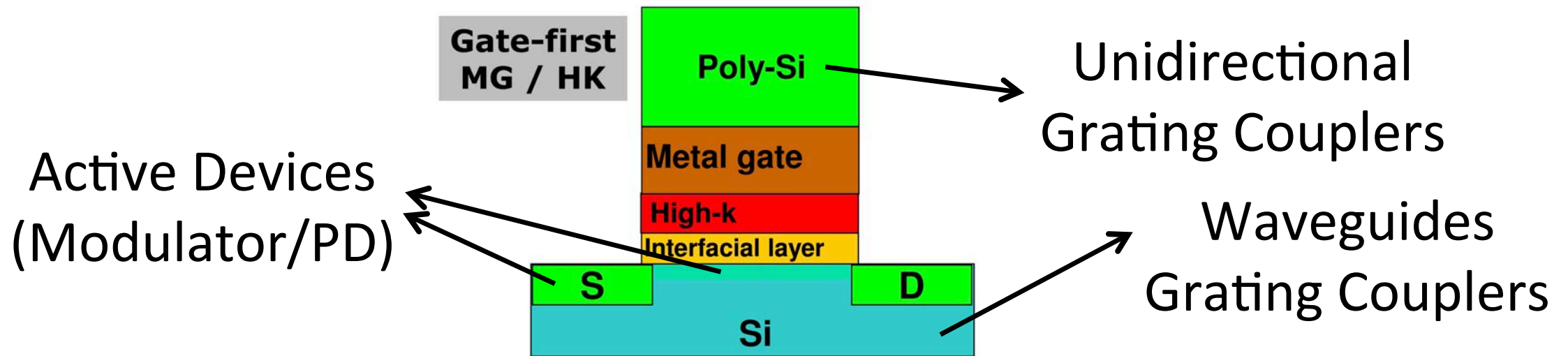
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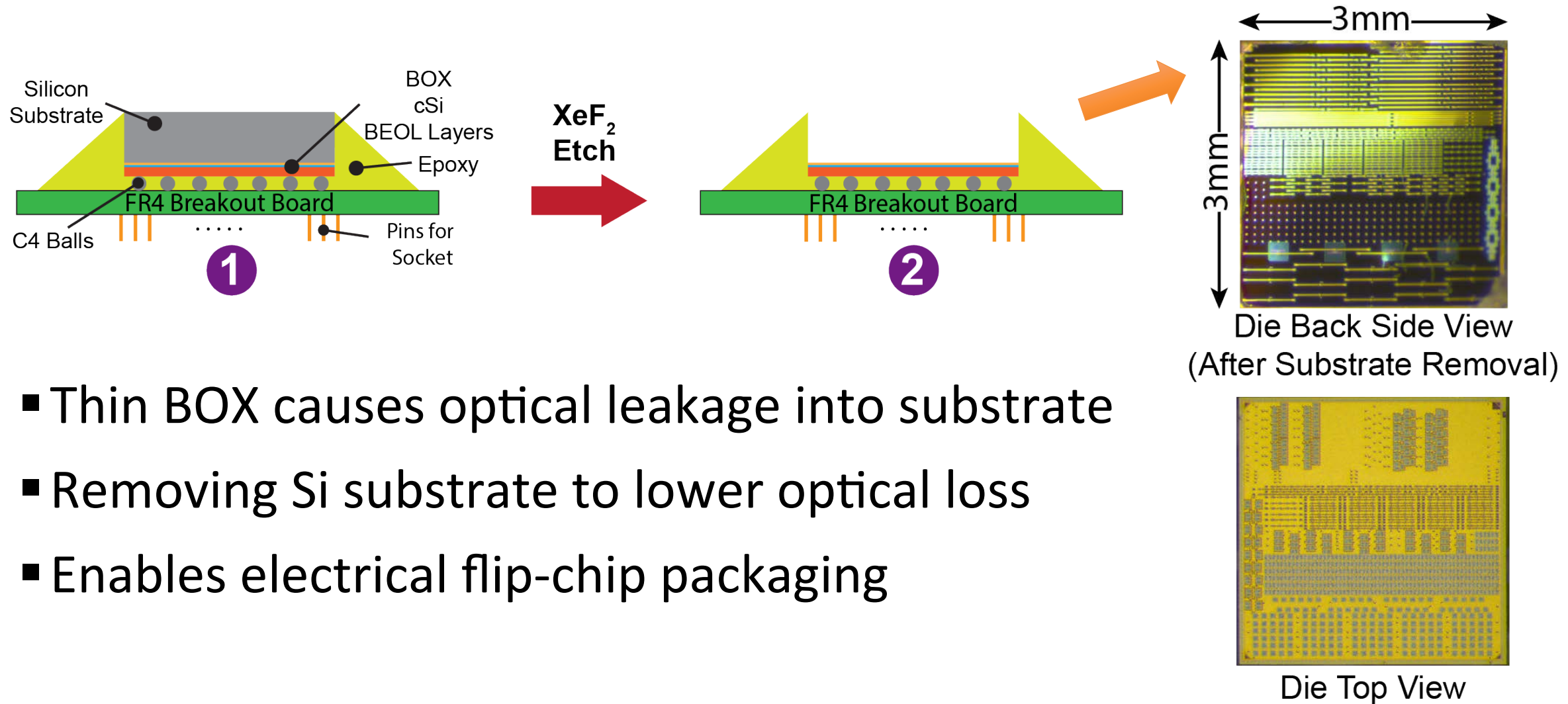
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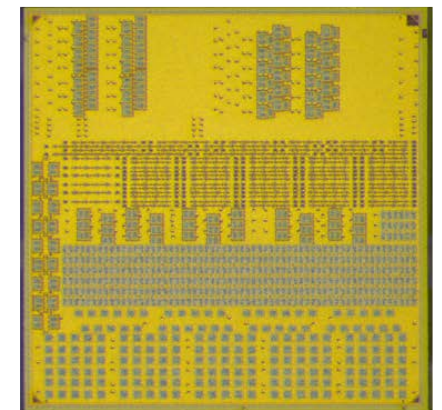
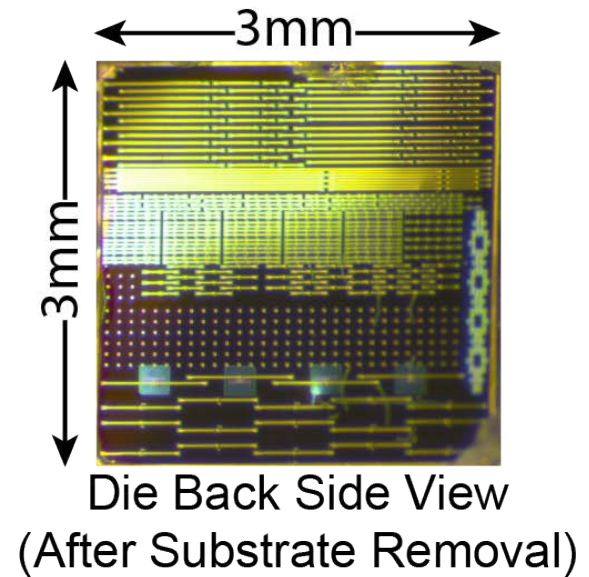
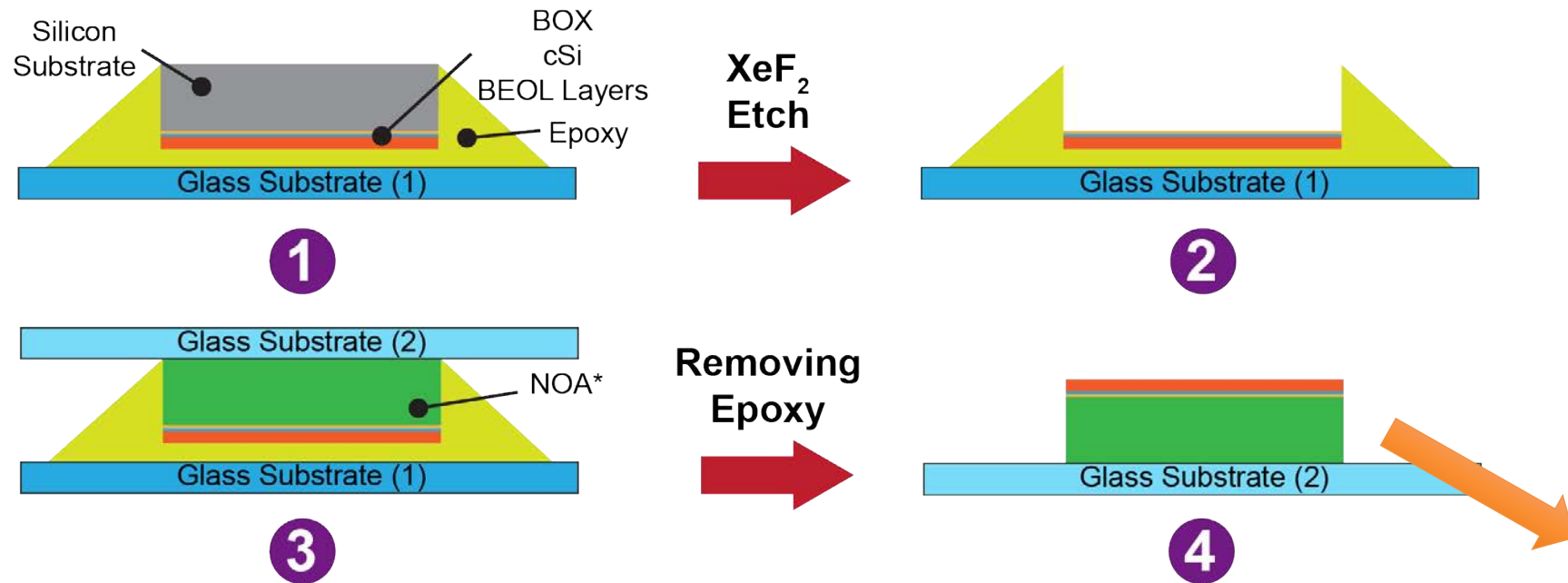
PMOS Cross-section [A. Kerber, SEMATECH AGST 2010]

Post-Processing with Electrical Packaging



- Thin BOX causes optical leakage into substrate
- Removing Si substrate to lower optical loss
- Enables electrical flip-chip packaging

Post-Processing for Probing

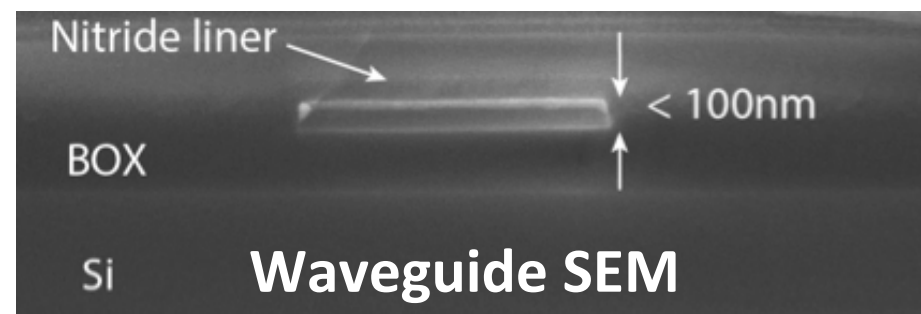
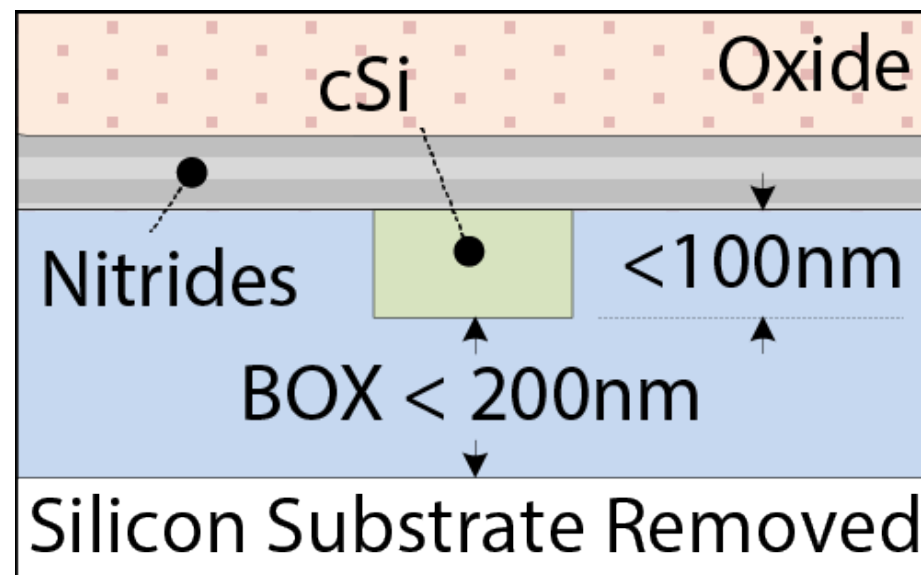


*NOA: None Optical Adhesive

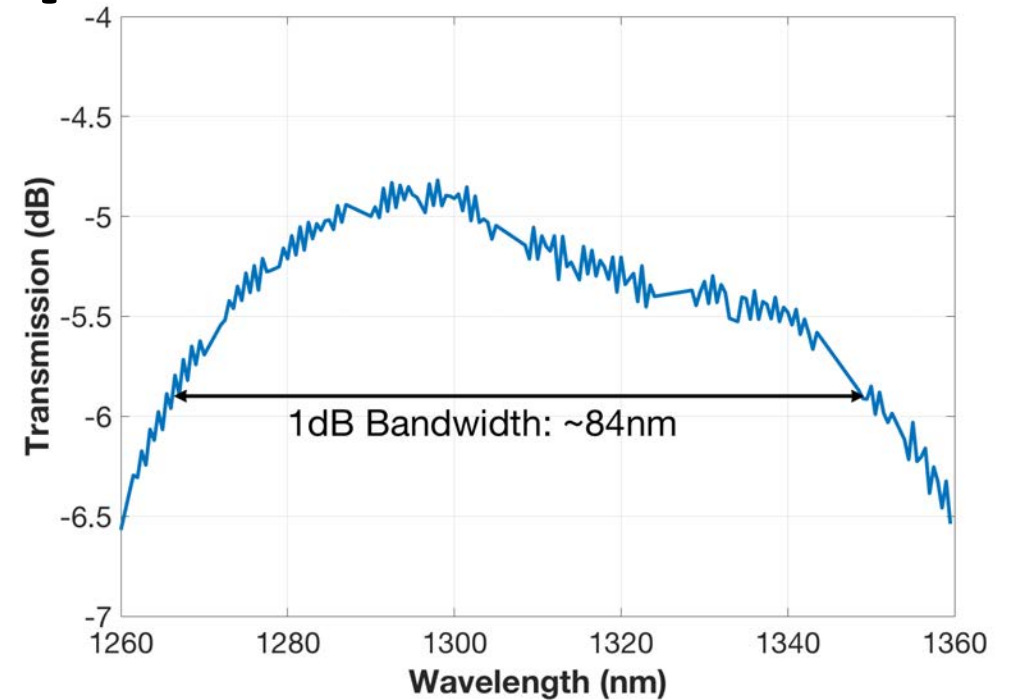
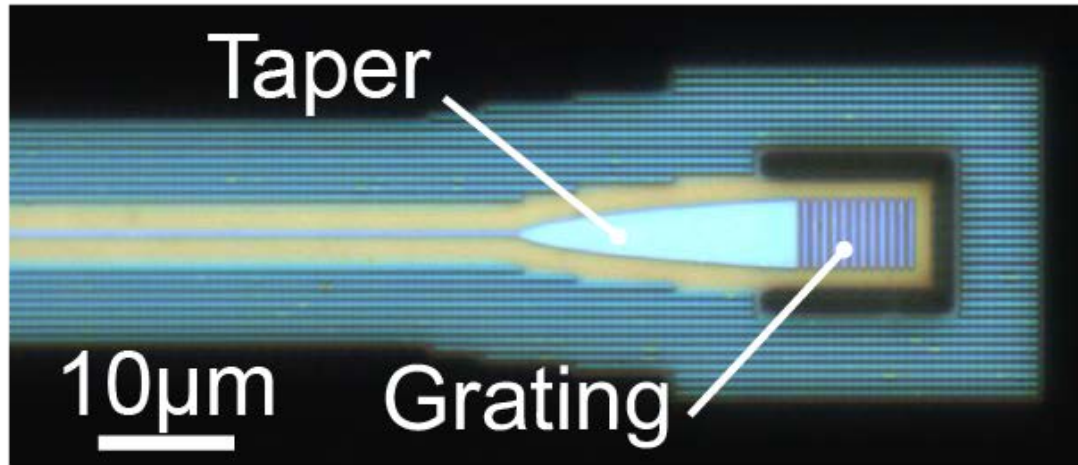
- Substrate transfer to access the pads for probing
- Bidirectional vertical grating couplers

Waveguides

- Built in crystalline silicon (cSi) layer by blocking dopings
- 3db/cm loss achieved in 45nm node [J.S. Orcutt, Opt. Express 2012]
- Measured loss in 32nm:
 - 25dB/cm @1310nm (O-band)
 - 20dB/cm @1550nm (C-band)
- Extra loss due to un-intentional dopings

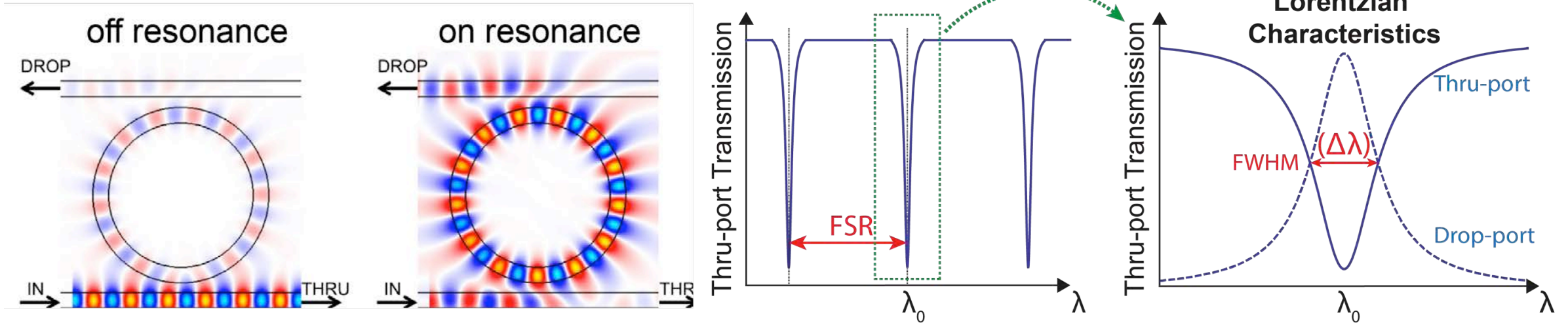


Bidirectional Grating Couplers



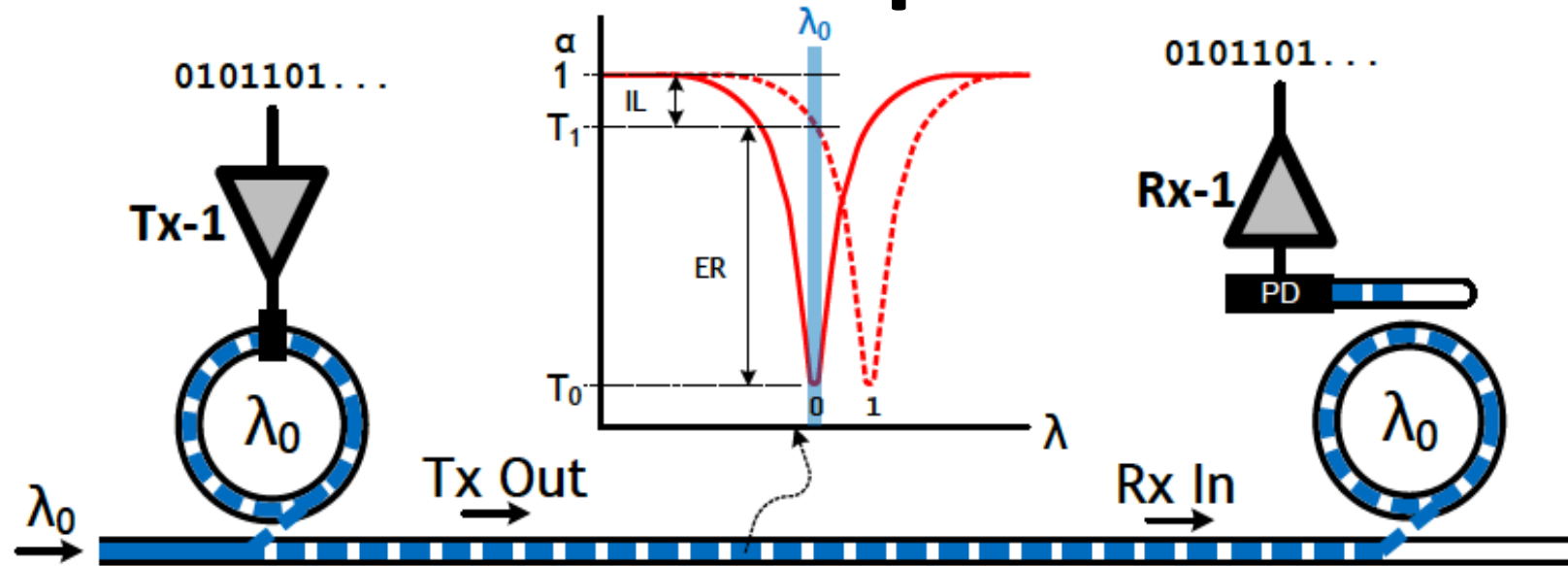
- Backside Coupling: 4.9dB loss with 84nm 1dB bandwidth
- Topside Coupling: 7.5dB loss (excess loss due to inter-layer dielectrics)
- Sub-2dB coupling can be achieved by adding polysilicon grating to break directionality symmetry [M. T. Wade, OI 2015]

Ring-resonators



- Resonance wavelength: $\lambda_0 = n_{\text{eff}}L/m$, $m = 1, 2, 3, \dots$
 - Q-factor: $Q = \lambda_0 / \Delta\lambda$
- Free spectral range (FSR) = λ^2/n_gL
 - Total available optical bandwidth in multi-wavelength communication
- 5 μm -radius high-Q rings in 32nm due to high lithography precision

Ring-resonator based Optical Transceivers



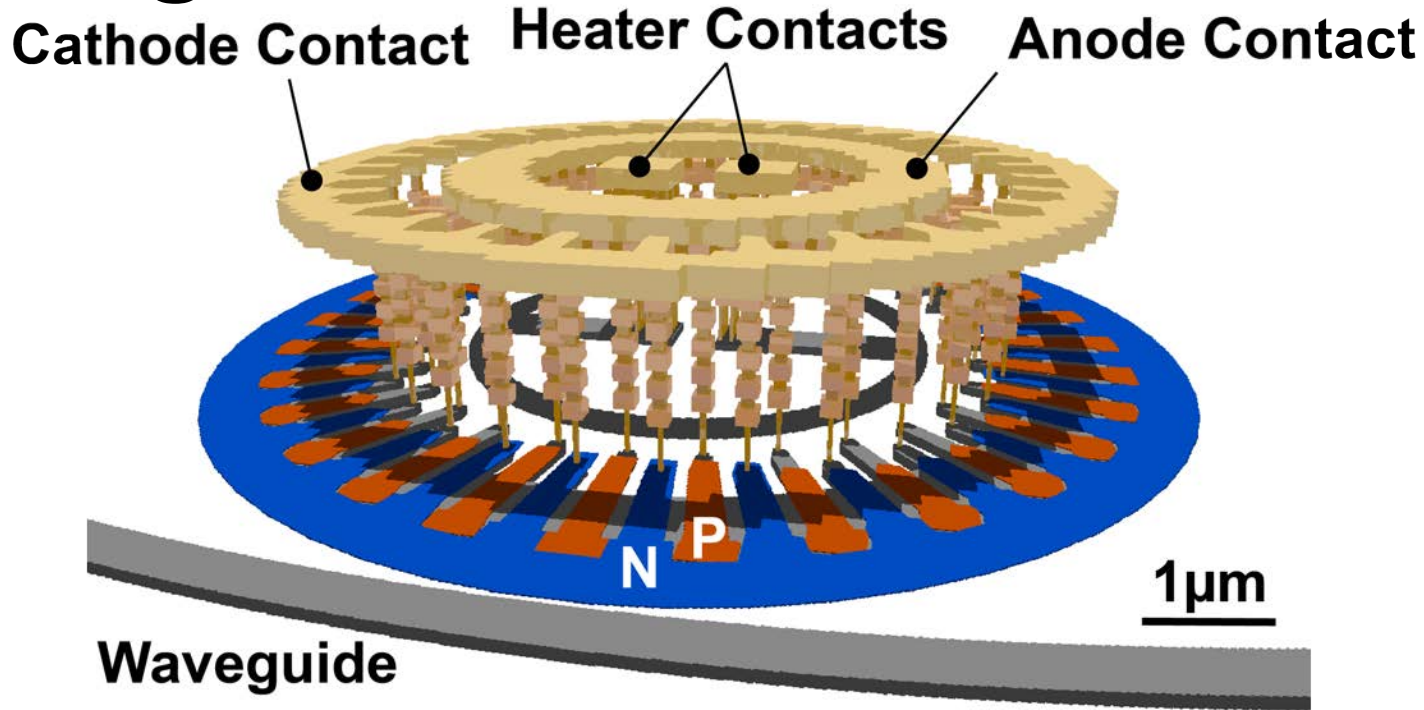
- Based on carrier plasma effect in silicon

[Courtesy of C. Sun]

- Modulation Scheme:

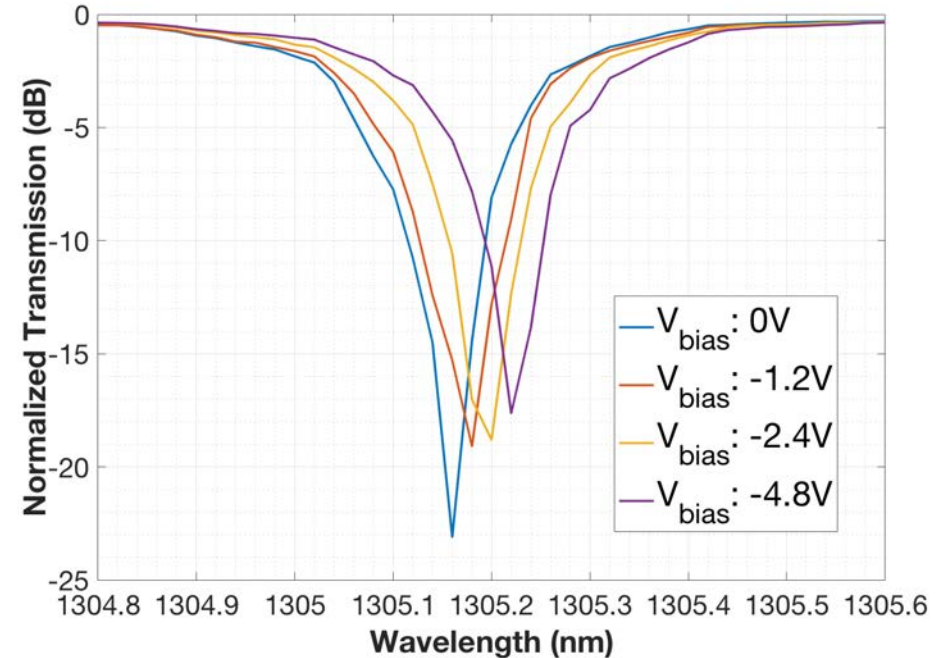
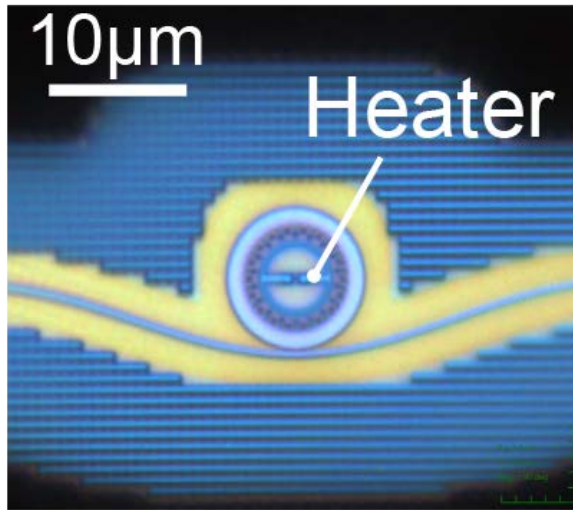
1. Deplete/Inject carriers using PN junctions
2. Δ free carriers \rightarrow Δ index of refraction
3. On-Off Keying (OOK) modulation in frequency domain

Spoked-ring Modulators



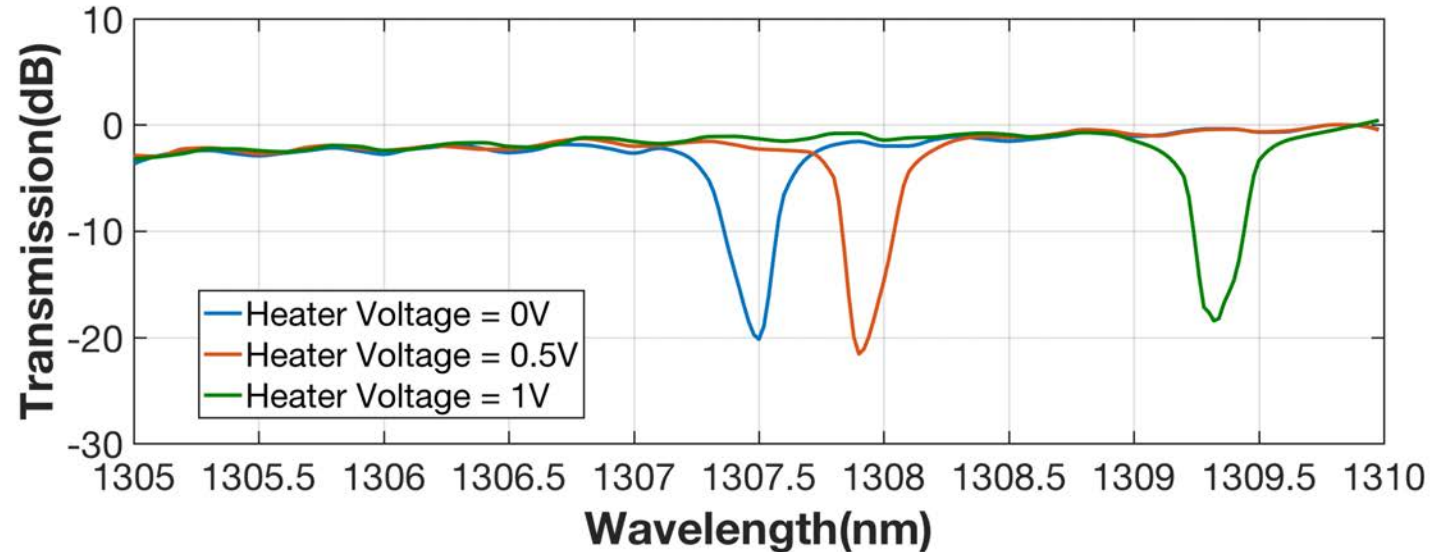
- Interleaved planar PN junctions
 - Enabled by advanced lithography of this process
- Spoked-shape contacts to avoid metallic optical loss

Spoked-ring Modulators



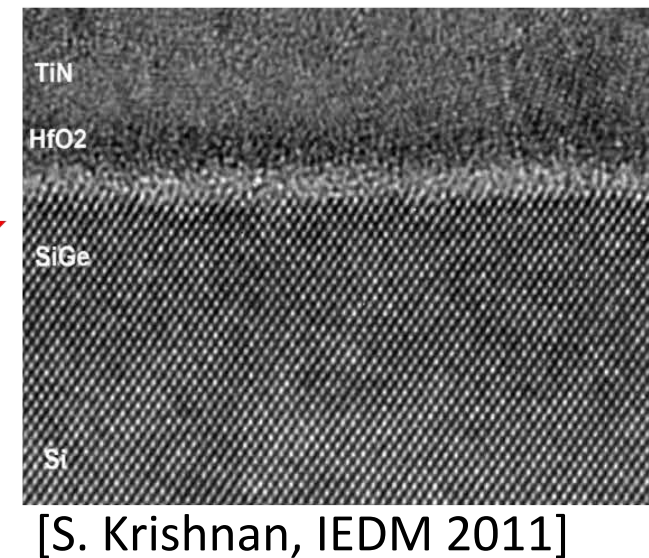
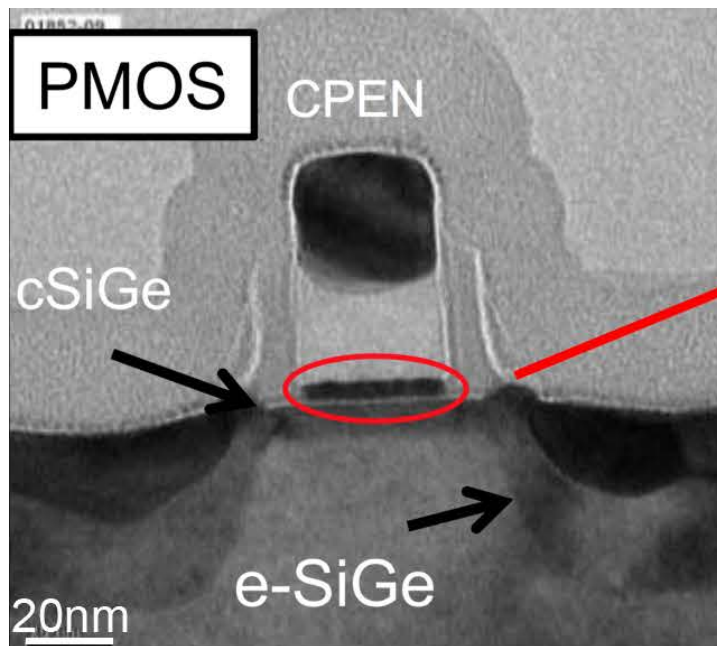
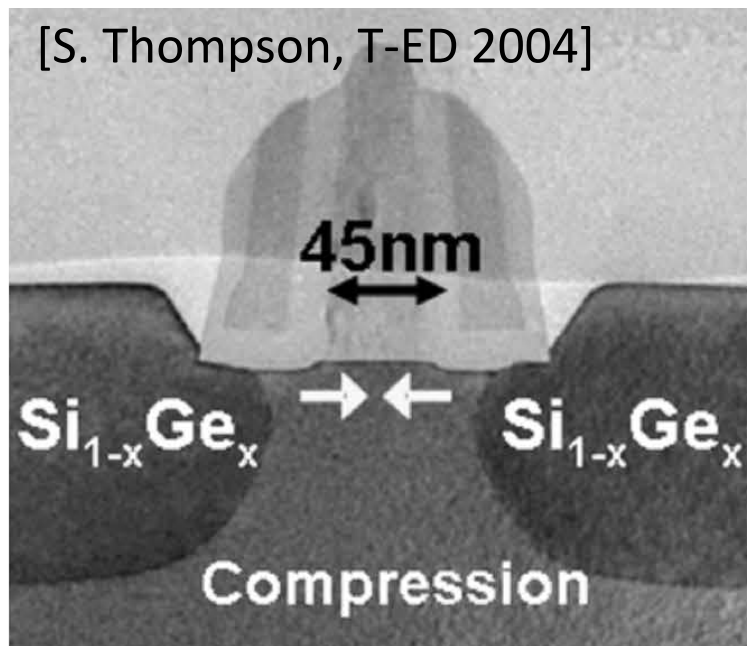
- 5 μm radius (FSR of 18.9 nm)
- Loaded Q-factor of 6k (intrinsic Q > 12k)
- 20 pm/V resonance shift efficiency in the depletion mode (reverse bias PN junctions)

Embedded Heater in Microrings



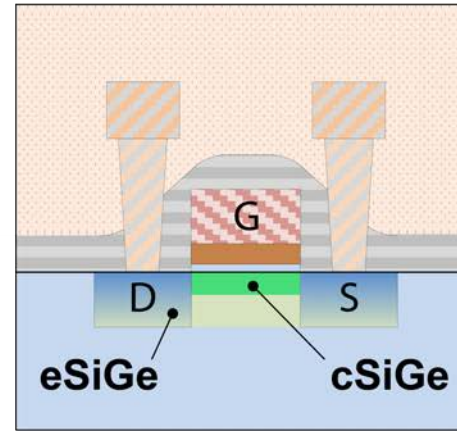
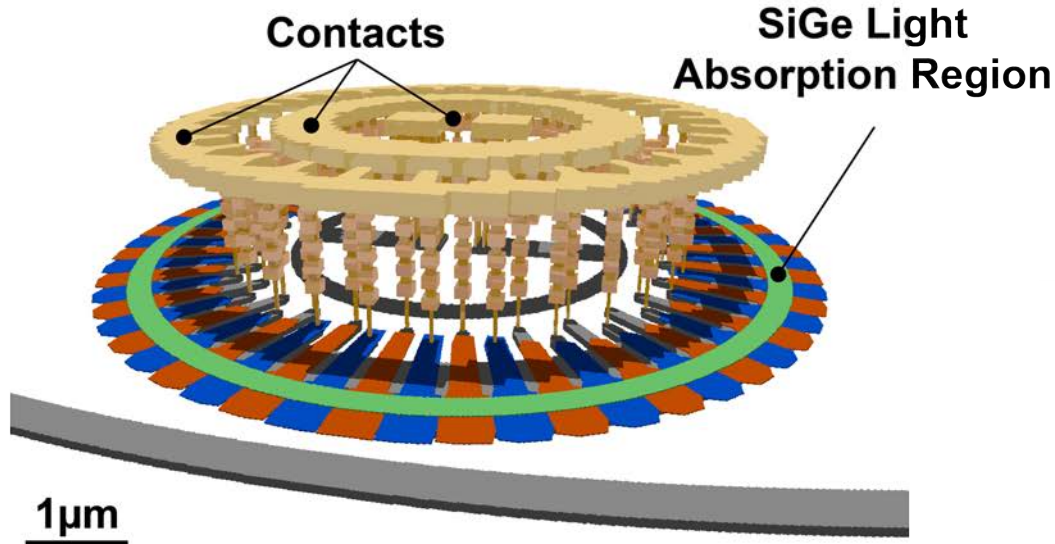
- Resistive heater in cSi layer with 500Ω resistance
- Used in tuning the ring for thermal and process variations
 - Essential for multi-wavelength systems [C. Sun, JSSC 2016]
- Heater tuning efficiency: 0.8nm/mW ($14\mu\text{W/GHz}$)
 - Flip-chip packaged chip has higher tuning efficiency ($3.7\mu\text{W/GHz}$)

O-band Light Detection

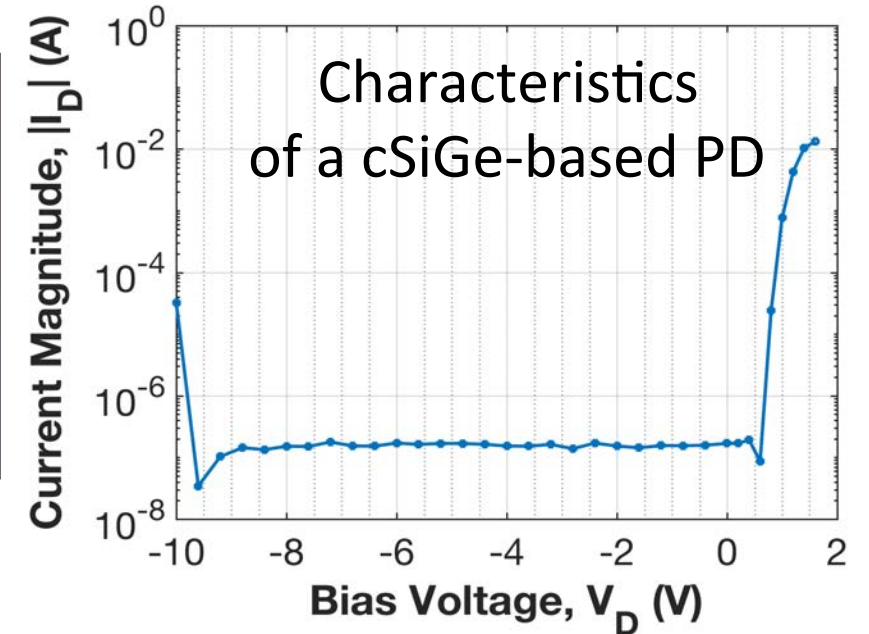


- SiGe layers originally used to improve PMOS performance
- Larger Ge% in cSiGe than eSiGe

Resonant Photo-detectors (PD)

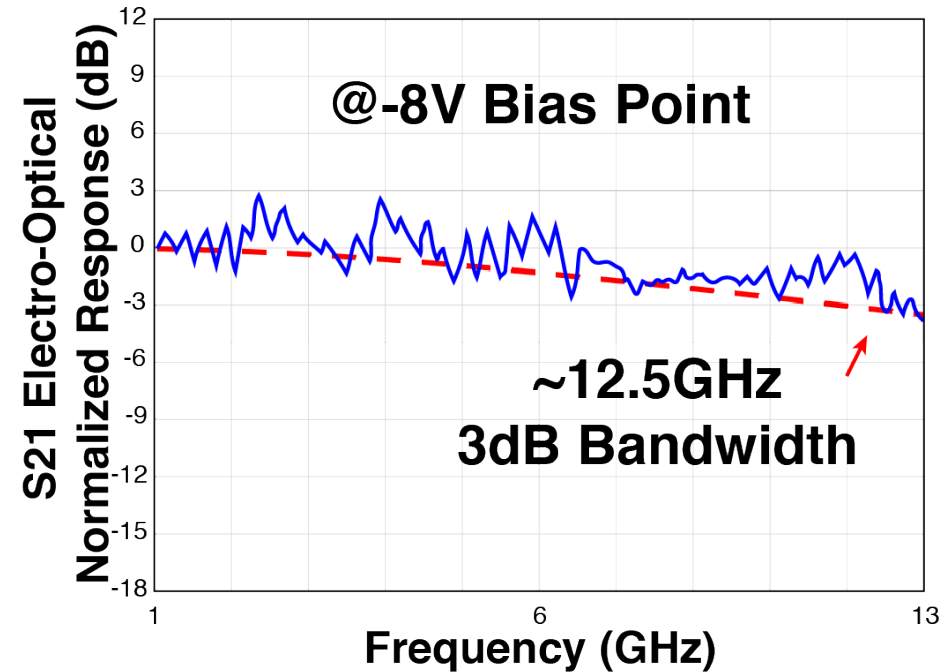
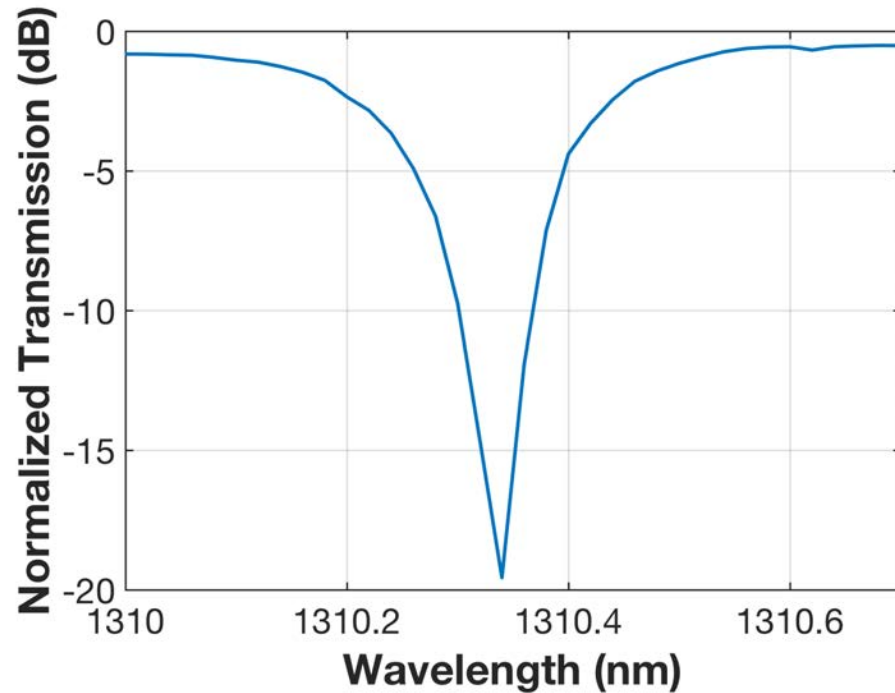


PMOS



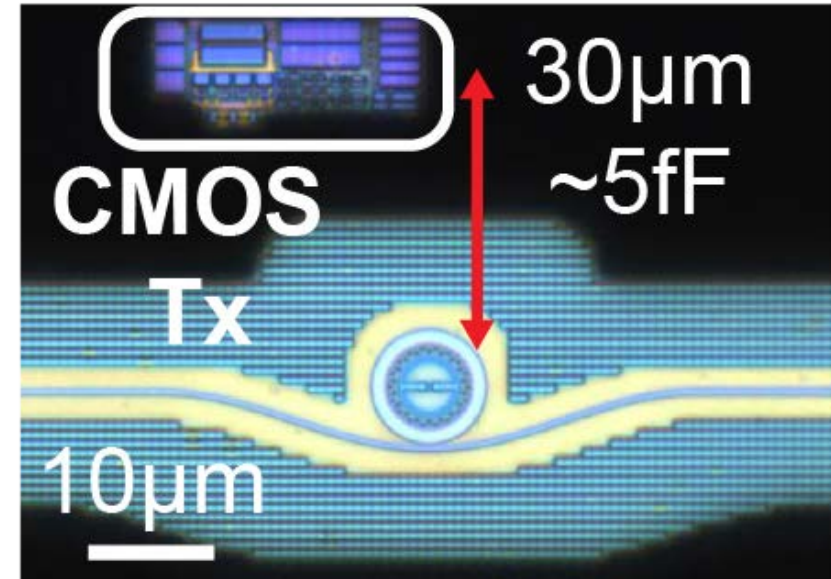
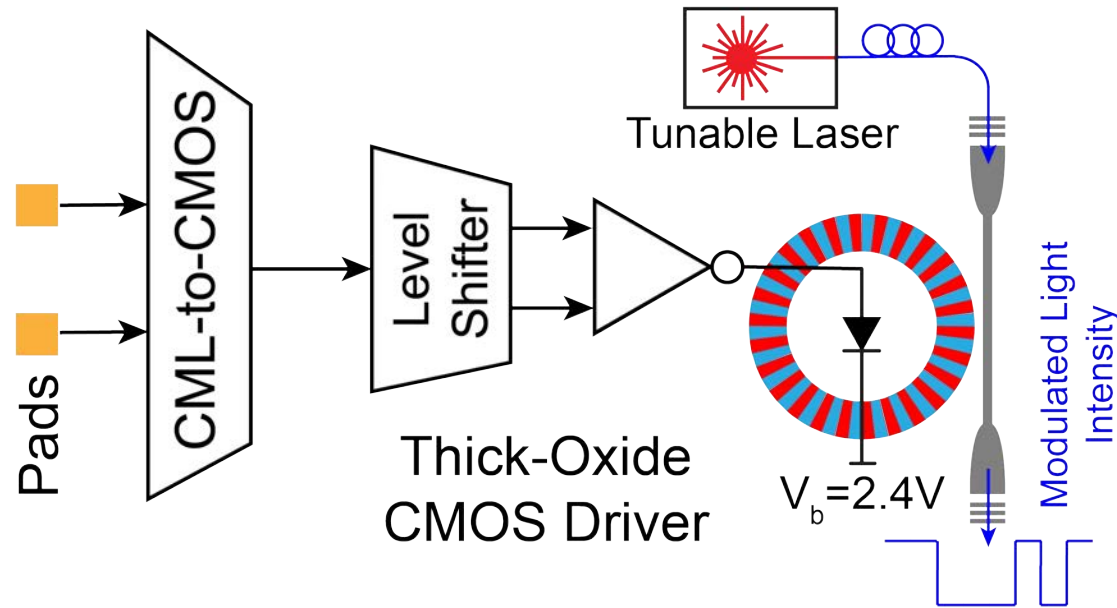
- Both types implemented with responsivities of:
 - eSiGe-based: 0.06 A/W
 - cSiGe-based: 0.13 A/W
- 150nA dark current

Resonant PD Characteristics



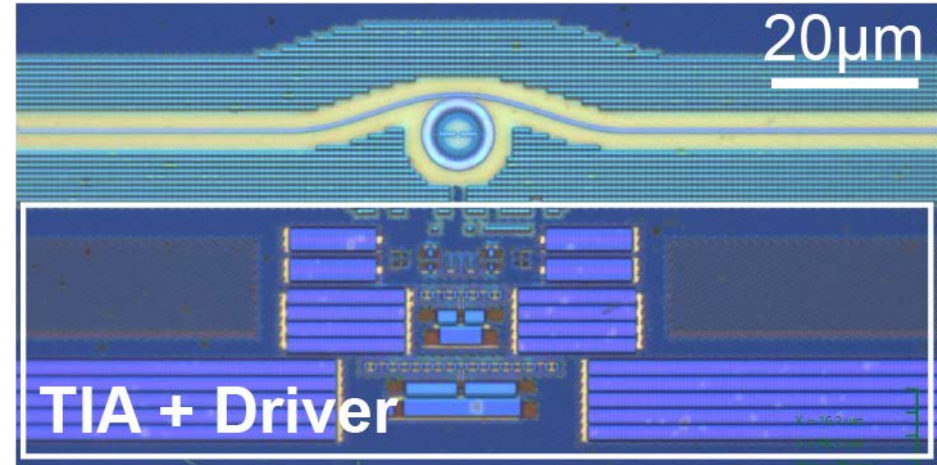
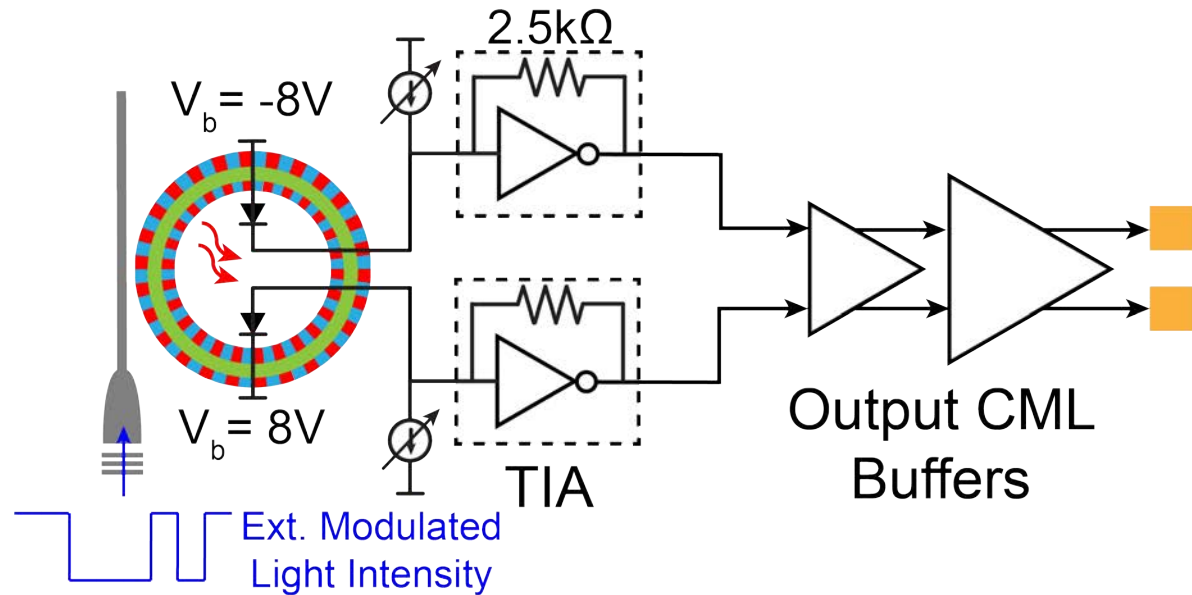
- Loaded Q-factors of 6.5k (intrinsic $Q > 15k$)
- 12.5GHz electro-optical bandwidth

Transmitter Block-diagram



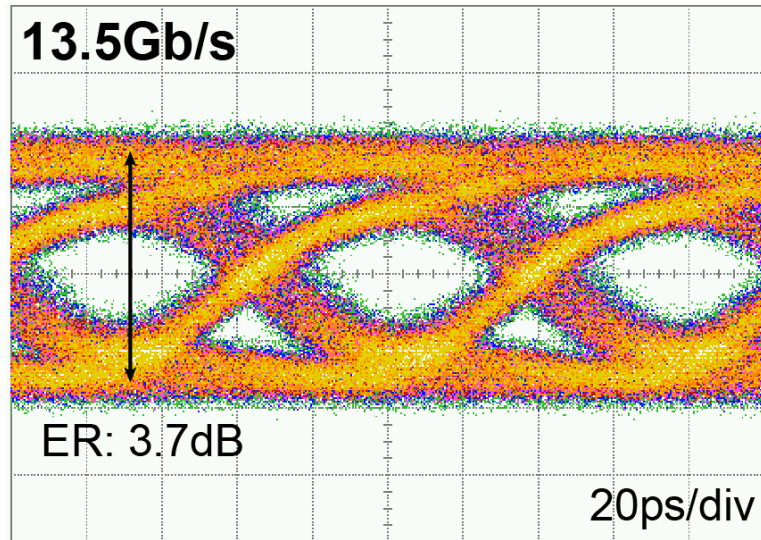
- High-swing (2.4V) thick-oxide drivers
- Depletion mode: 0V or -2.4V applied on PN junctions
- Electrical speed (>25Gb/s) with 30fF capacitance to drive

Receiver Block-diagram

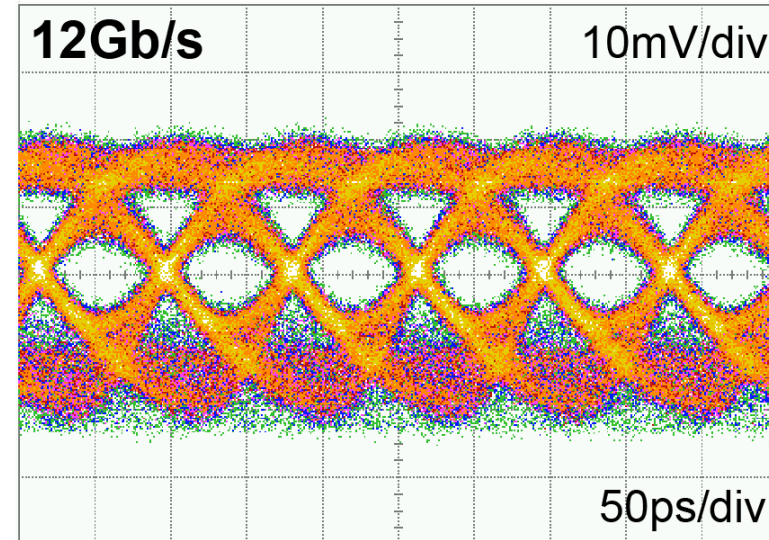


- Two-segmented resonant PD (Split PD)
 - Mitigates common-mode noise
- $13k\Omega$ with 5GHz electrical bandwidth (TIA gain: $4.5k\Omega$)
- Tested by externally modulated light

Transceivers Results



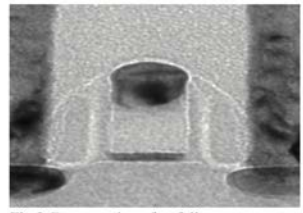
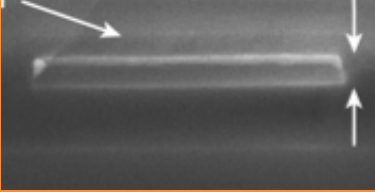
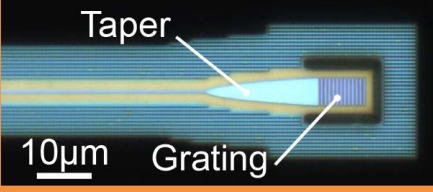
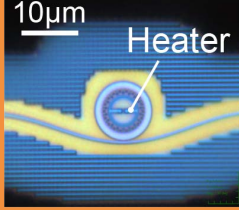

Transmitter eye-diagram



Receiver eye-diagram

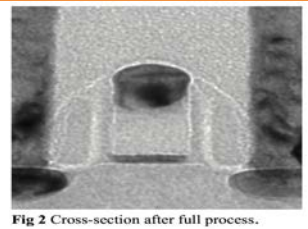
- **Transmitter:** 13.5Gb/s with extinction ratio (ER) of 3.7dB and insertion loss (IL) of 2.8dB
- **Receiver:** 12Gb/s (limited by TIA bandwidth)

Platform Summary

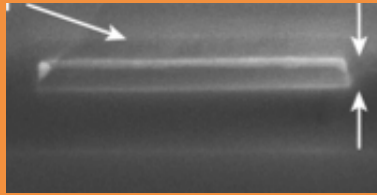
<p>Transistors</p>  <p><small>Fig 2 Cross-section after full process.</small> [B. Greene, VLSI 2009]</p>	<p>Waveguides</p> 	<p>Grating Couplers</p> 	<p>Ring Modulators</p> 	<p>Resonant PDs</p> 
<p>32nm SOI f_{\max}: 390/350GHz One of the fastest CMOS nodes with <5fF parasitic cap to photonic devices</p>	<p>Loss: 20db/cm</p>	<p>Loss: 4.9db (84nm 1-db BW)</p>	<p>Q-factor: 6k BW < 10GHz</p>	<p>Res: 0.13A/W BW: 12.5GHz</p>
	<p>Blocking all doping layers Loss: 3db/cm</p>	<p>Adding polysilicon grating (3dB improvement) Loss: Sub-2dB</p>	<p>Optimizing PN junction RC / lower waveguide loss Q-factor > 10k BW > 20GHz</p>	<p>Optimizing PN junction RC & SiGe width Res: 0.5A/W</p>

Platform Applications

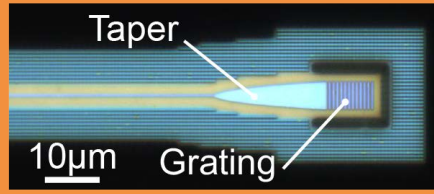
Transistors



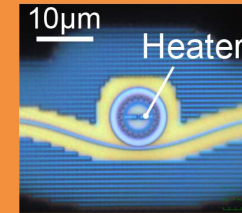
Waveguides



Grating Couplers



Ring Modulators



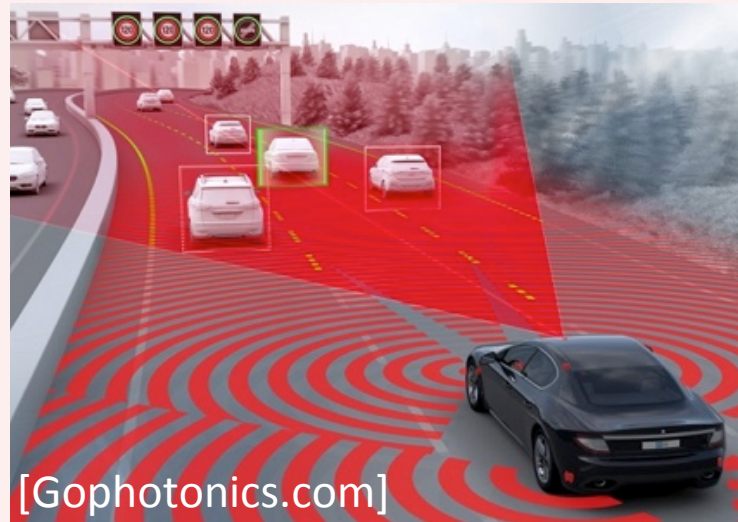
Resonant PDs



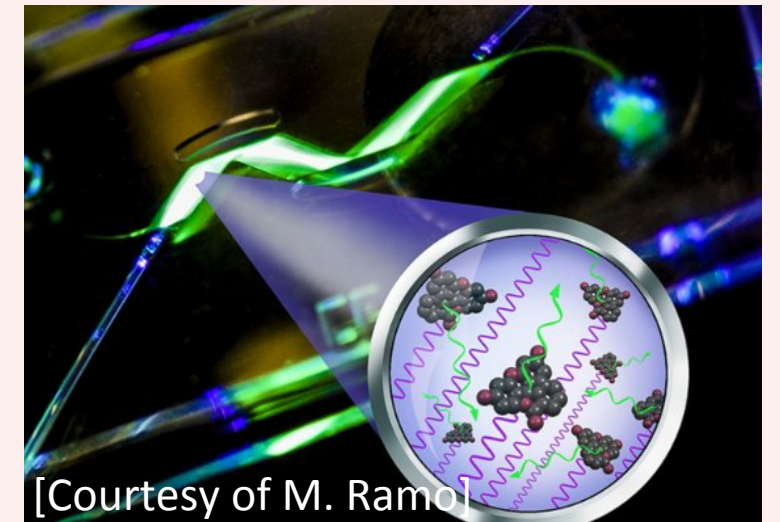
Computation



Imaging



Sensing & Bio



Conclusion

- Monolithic silicon photonics with fastest transistors
 - Demonstration of 12Gb/s O-band transceivers
- Continuation of “zero-change” approach to more advanced and complex (e.g. HKMG) SOI CMOS technologies
- Potentially revolutionize many applications despite slowdown in CMOS scaling
 - VLSI compute and network infrastructure just a start ...

Acknowledgment

This work was supported in part by DARPA (POEM Program) and the Berkeley Wireless Research Center (BWRC).

